

**Product Texts**

Base Polymer	Polyamide 6
Special Features	fast solidifying,easy release (demoulding),easy flow,laser etchable (light etching)
Typical Applications	housings,handles,various

<b>Mechanical properties</b>	<b>dry / cond</b>	<b>Unit</b>	<b>Test Standard</b>
<b>ISO Data</b>			
<sup>[C]</sup> Tensile Modulus	<b>3200 / 1000</b>	MPa	ISO 527
<sup>[C]</sup> Yield stress	<b>81 / 45</b>	MPa	ISO 527
<sup>[C]</sup> Yield strain	<b>3.5 / 22</b>	%	ISO 527
<sup>[C]</sup> Charpy impact strength, +23°C	<b>60 / N</b>	kJ/m <sup>2</sup>	ISO 179/1eU
<sup>[C]</sup> Charpy notched impact strength, +23°C	<b>5 / 25</b>	kJ/m <sup>2</sup>	ISO 179/1eA

[C]: CAMPUS

<b>Thermal properties</b>	<b>dry / cond</b>	<b>Unit</b>	<b>Test Standard</b>
<b>ISO Data</b>			
<sup>[C]</sup> Temp. of deflection under load, 1.80 MPa	<b>65 / *</b>	°C	ISO 75-1/-2
<sup>[C]</sup> Burning Behav. at 1.5 mm nom. thickn.	<b>V-2 / *</b>	class	IEC 60695-11-10
Thickness tested	<b>1.5 / *</b>	mm	-
Yellow Card available	<b>yes / *</b>	-	-

[C]: CAMPUS

<b>Other properties</b>	<b>dry / cond</b>	<b>Unit</b>	<b>Test Standard</b>
<sup>[C]</sup> Density	<b>1130 / -</b>	kg/m <sup>3</sup>	ISO 1183

[C]: CAMPUS

**Characteristics****Processing**

Injection Molding

**Applications**

Encapsulation

**Delivery form**

Black

**Regional Availability**

North America, Europe, Asia Pacific, Near East/Africa

**Features**

Laser Markable

**Other text information****Injection molding**

Pre-Drying Conditions	80 °C in a dry air (dessiccant) dryer for 2-12 h dependant on moisture content max. moisture content <0,15 %
Processing Injection Moulding	melt temperature 250-270 °C mould temperature 40-80 °C
Storage	dry, protected from light not above 30°C